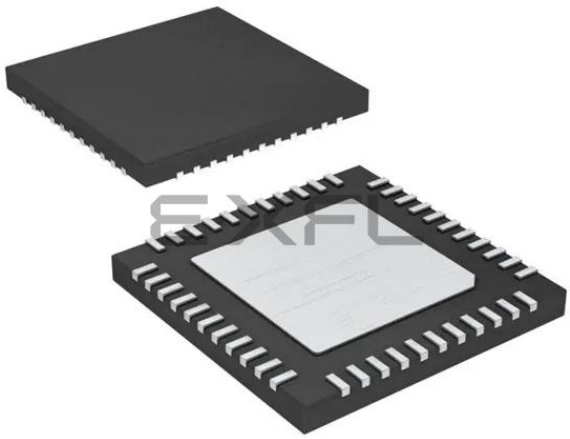
Microchip Technology - PIC32MX130F256D-V/ML Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx130f256d-v-ml

1.0 DEVICE OVERVIEW

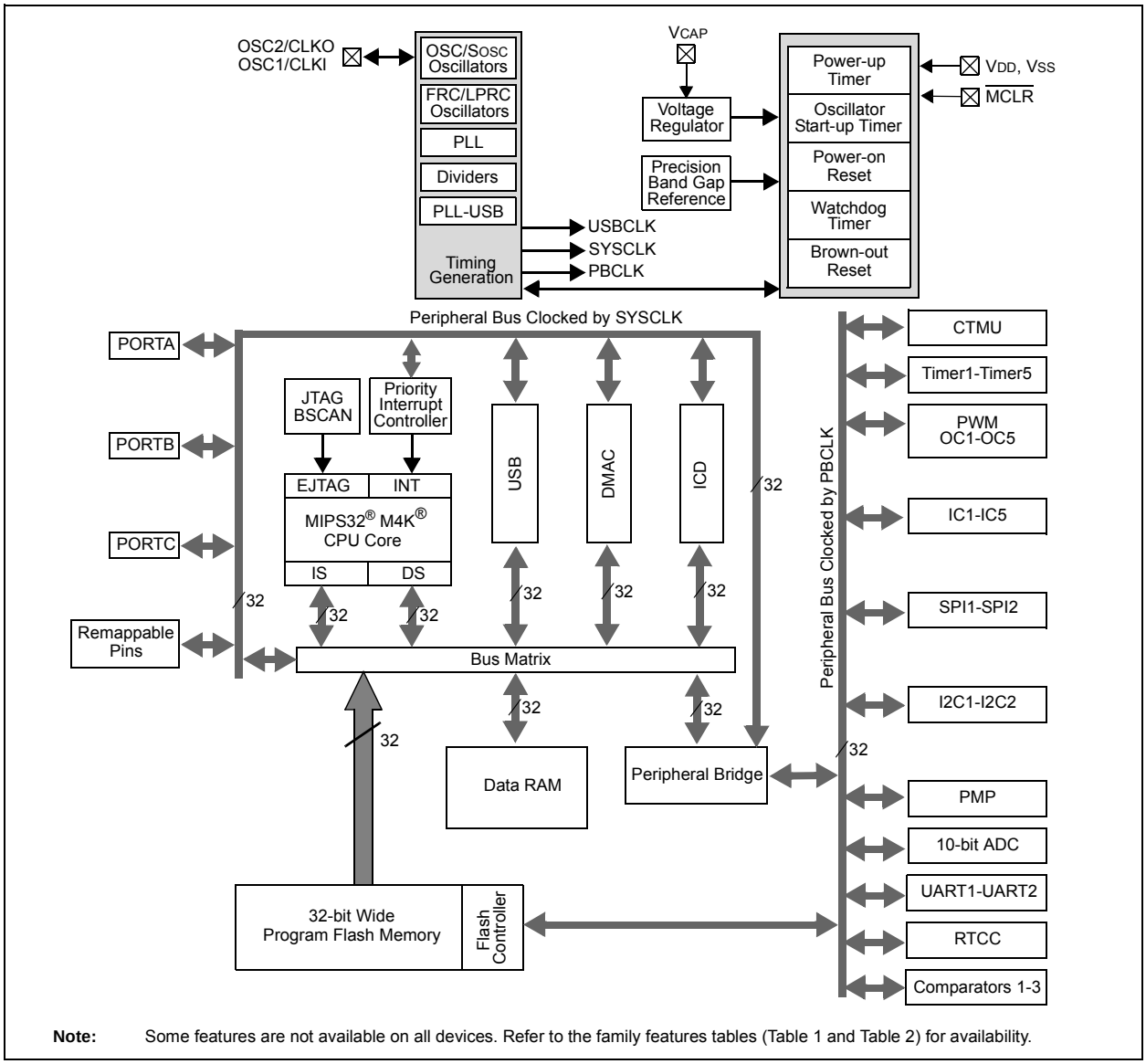
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This document contains device-specific information for PIC32MX1XX/2XX 28/36/44-pin Family devices.

Figure 1-1 illustrates a general block diagram of the core and peripheral modules in the PIC32MX1XX/2XX 28/36/44-pin Family of devices.

Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: BLOCK DIAGRAM



Note: Some features are not available on all devices. Refer to the family features tables (Table 1 and Table 2) for availability.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
RC0	—	—	3	25	I/O	ST	PORTC is a bidirectional I/O port
RC1	—	—	4	26	I/O	ST	
RC2	—	—	—	27	I/O	ST	
RC3	—	—	11	36	I/O	ST	
RC4	—	—	—	37	I/O	ST	
RC5	—	—	—	38	I/O	ST	
RC6	—	—	—	2	I/O	ST	
RC7	—	—	—	3	I/O	ST	
RC8	—	—	—	4	I/O	ST	
RC9	—	—	20	5	I/O	ST	
T1CK	9	12	10	34	I	ST	Timer1 external clock input
T2CK	PPS	PPS	PPS	PPS	I	ST	Timer2 external clock input
T3CK	PPS	PPS	PPS	PPS	I	ST	Timer3 external clock input
T4CK	PPS	PPS	PPS	PPS	I	ST	Timer4 external clock input
T5CK	PPS	PPS	PPS	PPS	I	ST	Timer5 external clock input
$\overline{U1CTS}$	PPS	PPS	PPS	PPS	I	ST	UART1 clear to send
$\overline{U1RTS}$	PPS	PPS	PPS	PPS	O	—	UART1 ready to send
U1RX	PPS	PPS	PPS	PPS	I	ST	UART1 receive
U1TX	PPS	PPS	PPS	PPS	O	—	UART1 transmit
$\overline{U2CTS}$	PPS	PPS	PPS	PPS	I	ST	UART2 clear to send
$\overline{U2RTS}$	PPS	PPS	PPS	PPS	O	—	UART2 ready to send
U2RX	PPS	PPS	PPS	PPS	I	ST	UART2 receive
U2TX	PPS	PPS	PPS	PPS	O	—	UART2 transmit
SCK1	22	25	28	14	I/O	ST	Synchronous serial clock input/output for SPI1
SDI1	PPS	PPS	PPS	PPS	I	ST	SPI1 data in
SDO1	PPS	PPS	PPS	PPS	O	—	SPI1 data out
$\overline{SS1}$	PPS	PPS	PPS	PPS	I/O	ST	SPI1 slave synchronization or frame pulse I/O
SCK2	23	26	29	15	I/O	ST	Synchronous serial clock input/output for SPI2
SDI2	PPS	PPS	PPS	PPS	I	ST	SPI2 data in
SDO2	PPS	PPS	PPS	PPS	O	—	SPI2 data out
$\overline{SS2}$	PPS	PPS	PPS	PPS	I/O	ST	SPI2 slave synchronization or frame pulse I/O
SCL1	14	17	18	44	I/O	ST	Synchronous serial clock input/output for I2C1

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
PMA0	7	10	8	3	I/O	TTL/ST	Parallel Master Port Address bit 0 input (Buffered Slave modes) and output (Master modes)
PMA1	9	12	10	2	I/O	TTL/ST	Parallel Master Port Address bit 1 input (Buffered Slave modes) and output (Master modes)
PMA2		—	—	27	O	—	Parallel Master Port address (Demultiplexed Master modes)
PMA3		—	—	38	O	—	
PMA4		—	—	37	O	—	
PMA5		—	—	4	O	—	
PMA6		—	—	5	O	—	
PMA7		—	—	13	O	—	
PMA8		—	—	32	O	—	
PMA9		—	—	35	O	—	
PMA10		—	—	12	O	—	
PMCS1	23	26	29	15	O	—	Parallel Master Port Chip Select 1 strobe
PMD0	20(2)	23(2)	26(2)	10(2)	I/O	TTL/ST	Parallel Master Port data (Demultiplexed Master mode) or address/data (Multiplexed Master modes)
	1(3)	4(3)	35(3)	21(3)			
PMD1	19(2)	22(2)	25(2)	9(2)	I/O	TTL/ST	
	2(3)	5(3)	36(3)	22(3)			
PMD2	18(2)	21(2)	24(2)	8(2)	I/O	TTL/ST	
	3(3)	6(3)	1(3)	23(3)			
PMD3	15	18	19	1	I/O	TTL/ST	
PMD4	14	17	18	44	I/O	TTL/ST	
PMD5	13	16	17	43	I/O	TTL/ST	
PMD6	12(2)	15(2)	16(2)	42(2)	I/O	TTL/ST	
	28(3)	3(3)	34(3)	20(3)			
PMD7	11(2)	14(2)	15(2)	41(2)	I/O	TTL/ST	
	27(3)	2(3)	33(3)	19(3)			
PMRD	21	24	27	11	O	—	Parallel Master Port read strobe
PMWR	22(2)	25(2)	28(2)	14(2)	O	—	Parallel Master Port write strobe
	4(3)	7(3)	2(3)	24(3)			
VBUS	12(3)	15(3)	16(3)	42(3)	I	Analog	USB bus power monitor
VUSB3V3	20(3)	23(3)	26(3)	10(3)	P	—	USB internal transceiver supply. This pin must be connected to VDD.
VBUSON	22(3)	25(3)	28(3)	14(3)	O	—	USB Host and OTG bus power control output
D+	18(3)	21(3)	24(3)	8(3)	I/O	Analog	USB D+
D-	19(3)	22(3)	25(3)	9(3)	I/O	Analog	USB D-

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
$\overline{MCLR}$	26	1	32	18	I/P	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	25	28	31	17	P	—	Positive supply for analog modules. This pin must be connected at all times.
AVSS	24	27	30	16	P	—	Ground reference for analog modules
VDD	10	13	5, 13, 14, 23	28, 40	P	—	Positive supply for peripheral logic and I/O pins
VCAP	17	20	22	7	P	—	CPU logic filter capacitor connection
VSS	5, 16	8, 19	6, 12, 21	6, 29, 39	P	—	Ground reference for logic and I/O pins. This pin must be connected at all times.
VREF+	27	2	33	19	I	Analog	Analog voltage reference (high) input
VREF-	28	3	34	20	I	Analog	Analog voltage reference (low) input

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

Coprocessor 0 also contains the logic for identifying and managing exceptions. Exceptions can be caused by a variety of sources, including alignment errors in data, external events or program errors. Table 3-3 lists the exception types in order of priority.

TABLE 3-3: MIPS32® M4K® PROCESSOR CORE EXCEPTION TYPES

Exception	Description
Reset	Assertion $\overline{\text{MCLR}}$ or a Power-on Reset (POR).
DSS	EJTAG debug single step.
DINT	EJTAG debug interrupt. Caused by the assertion of the external *EJ_DINT* input or by setting the EjtagBrk bit in the ECR register.
NMI	Assertion of NMI signal.
Interrupt	Assertion of unmasked hardware or software interrupt signal.
DIB	EJTAG debug hardware instruction break matched.
AdEL	Fetch address alignment error. Fetch reference to protected address.
IBE	Instruction fetch bus error.
DBp	EJTAG breakpoint (execution of SDBBP instruction).
Sys	Execution of SYSCALL instruction.
Bp	Execution of BREAK instruction.
RI	Execution of a reserved instruction.
CpU	Execution of a coprocessor instruction for a coprocessor that is not enabled.
CEU	Execution of a CorExtend instruction when CorExtend is not enabled.
Ov	Execution of an arithmetic instruction that overflowed.
Tr	Execution of a trap (when trap condition is true).
DDBL/DDBS	EJTAG Data Address Break (address only) or EJTAG data value break on store (address + value).
AdEL	Load address alignment error. Load reference to protected address.
AdES	Store address alignment error. Store to protected address.
DBE	Load or store bus error.
DDBL	EJTAG data hardware breakpoint matched in load data compare.

3.3 Power Management

The MIPS M4K processor core offers many power management features, including low-power design, active power management and power-down modes of operation. The core is a static design that supports slowing or Halting the clocks, which reduces system power consumption during Idle periods.

3.3.1 INSTRUCTION-CONTROLLED POWER MANAGEMENT

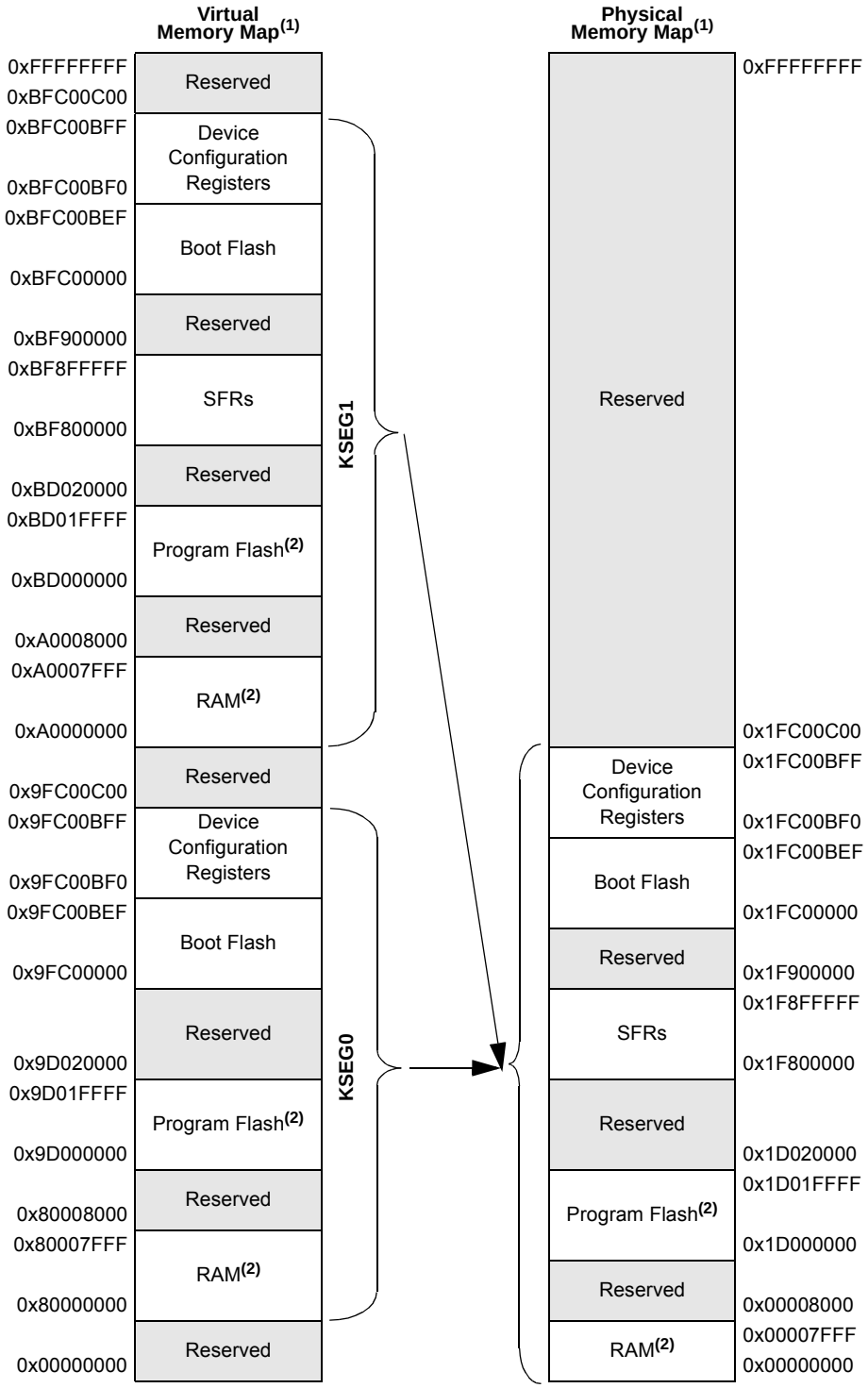
The mechanism for invoking Power-Down mode is through execution of the WAIT instruction. For more information on power management, see **Section 26.0 "Power-Saving Features"**.

3.4 EJTAG Debug Support

The MIPS M4K processor core provides an Enhanced JTAG (EJTAG) interface for use in the software debug of application and kernel code. In addition to standard User mode and Kernel modes of operation, the M4K core provides a Debug mode that is entered after a debug exception (derived from a hardware breakpoint, single-step exception, etc.) is taken and continues until a Debug Exception Return (DERET) instruction is executed. During this time, the processor executes the debug exception handler routine.

The EJTAG interface operates through the Test Access Port (TAP), a serial communication port used for transferring test data in and out of the core. In addition to the standard JTAG instructions, special instructions defined in the EJTAG specification define which registers are selected and how they are used.

FIGURE 4-4: MEMORY MAP ON RESET FOR PIC32MX150/250 DEVICES (32 KB RAM, 128 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 4-1: BMXCON: BUS MATRIX CONFIGURATION REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	—	—	—	BMX ERRIXI	BMX ERRICD	BMX ERRDMA	BMX ERRDS	BMX ERRIS
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	R/W-1	U-0	U-0	U-0	R/W-0	R/W-0	R/W-1
	—	BMX WSDRM	—	—	—	BMXARB<2:0>		

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared

bit 31-21 **Unimplemented:** Read as '0'

bit 20 **BMXERRIXI:** Enable Bus Error from IXI bit
1 = Enable bus error exceptions for unmapped address accesses initiated from IXI shared bus
0 = Disable bus error exceptions for unmapped address accesses initiated from IXI shared bus

bit 19 **BMXERRICD:** Enable Bus Error from ICD Debug Unit bit
1 = Enable bus error exceptions for unmapped address accesses initiated from ICD
0 = Disable bus error exceptions for unmapped address accesses initiated from ICD

bit 18 **BMXERRDMA:** Bus Error from DMA bit
1 = Enable bus error exceptions for unmapped address accesses initiated from DMA
0 = Disable bus error exceptions for unmapped address accesses initiated from DMA

bit 17 **BMXERRDS:** Bus Error from CPU Data Access bit (disabled in Debug mode)
1 = Enable bus error exceptions for unmapped address accesses initiated from CPU data access
0 = Disable bus error exceptions for unmapped address accesses initiated from CPU data access

bit 16 **BMXERRIS:** Bus Error from CPU Instruction Access bit (disabled in Debug mode)
1 = Enable bus error exceptions for unmapped address accesses initiated from CPU instruction access
0 = Disable bus error exceptions for unmapped address accesses initiated from CPU instruction access

bit 15-7 **Unimplemented:** Read as '0'

bit 6 **BMXWSDRM:** CPU Instruction or Data Access from Data RAM Wait State bit
1 = Data RAM accesses from CPU have one wait state for address setup
0 = Data RAM accesses from CPU have zero wait states for address setup

bit 5-3 **Unimplemented:** Read as '0'

bit 2-0 **BMXARB<2:0>:** Bus Matrix Arbitration Mode bits
111 = Reserved (using these Configuration modes will produce undefined behavior)
•
•
•
011 = Reserved (using these Configuration modes will produce undefined behavior)
010 = Arbitration Mode 2
001 = Arbitration Mode 1 (default)
000 = Arbitration Mode 0

5.1 Flash Controller Control Registers

TABLE 5-1: FLASH CONTROLLER REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F400	NVMCON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	WR	WREN	WRERR	LVDERR	LVDSTAT	—	—	—	—	—	—	—	NVMOP<3:0>				0000
F410	NVMKEY	31:16	NVMKEY<31:0>																0000
		15:0																	0000
F420	NVMADDR(1)	31:16	NVMADDR<31:0>																0000
		15:0																	0000
F430	NVMDATA	31:16	NVMDATA<31:0>																0000
		15:0																	0000
F440	NVMSRCADDR	31:16	NVMSRCADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

REGISTER 10-11: U1CON: USB CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-x	R-x	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	JSTATE	SE0	PKTDIS(4) / TOKBUSY(1,5)	USBRST	HOSTEN(2)	RESUME(3)	PPBRST	USBEN(4) / SOFEN(5)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **JSTATE:** Live Differential Receiver JSTATE flag bit
1 = JSTATE was detected on the USB
0 = No JSTATE was detected

bit 6 **SE0:** Live Single-Ended Zero flag bit
1 = Single-Ended Zero was detected on the USB
0 = No Single-Ended Zero was detected

bit 5 **PKTDIS:** Packet Transfer Disable bit(4)
1 = Token and packet processing is disabled (set upon SETUP token received)
0 = Token and packet processing is enabled

TOKBUSY: Token Busy Indicator bit(1,5)
1 = Token is being executed by the USB module
0 = No token is being executed

bit 4 **USBRST:** Module Reset bit(5)
1 = USB reset generated
0 = USB reset terminated

bit 3 **HOSTEN:** Host Mode Enable bit(2)
1 = USB host capability is enabled
0 = USB host capability is disabled

bit 2 **RESUME:** RESUME Signaling Enable bit(3)
1 = RESUME signaling is activated
0 = RESUME signaling is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 10-15).

2: All host control logic is reset any time that the value of this bit is toggled.

3: Software must set RESUME for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a Low-Speed EOP to the RESUME signaling when this bit is cleared.

4: Device mode.

5: Host mode.

REGISTER 10-18: U1BDTP2: USB BUFFER DESCRIPTOR TABLE PAGE 2 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BDTPTRH<23:16>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **BDTPTRH<23:16>:** Buffer Descriptor Table Base Address bits

This 8-bit value provides address bits 23 through 16 of the Buffer Descriptor Table base address, which defines the starting location of the Buffer Descriptor Table in system memory.

The 32-bit Buffer Descriptor Table base address is 512-byte aligned.

REGISTER 10-19: U1BDTP3: USB BUFFER DESCRIPTOR TABLE PAGE 3 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BDTPTRU<31:24>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **BDTPTRU<31:24>:** Buffer Descriptor Table Base Address bits

This 8-bit value provides address bits 31 through 24 of the Buffer Descriptor Table base address, defines the starting location of the Buffer Descriptor Table in system memory.

The 32-bit Buffer Descriptor Table base address is 512-byte aligned.

NOTES:

20.1 PMP Control Registers

TABLE 20-1: PARALLEL MASTER PORT REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
7000	PMCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	ADRMUX<1:0>		PMPTTL	PTWREN	PTRDEN	CSF<1:0>		ALP	—	CS1P	—	WRSP	RDSP	0000
7010	PMMODE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BUSY	IRQM<1:0>		INCM<1:0>		—	MODE<1:0>		WAITB<1:0>		WAITM<3:0>				WAITE<1:0>		0000
7020	PMADDR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	CS1 / ADDR14	—	—	—	ADDR<10:0>											0000
7030	PMDOUT	31:16	DATAOUT<31:0>																0000
		15:0																	0000
7040	PMDIN	31:16	DATAIN<31:0>																0000
		15:0																	0000
7050	PMAEN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	PTEN14	—	—	—	PTEN<10:0>											0000
7060	PMSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	IBF	IBOV	—	—	IB3F	IB2F	IB1F	IB0F	OBE	OBUF	—	—	OB3E	OB2E	OB1E	OB0E	008F

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

21.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

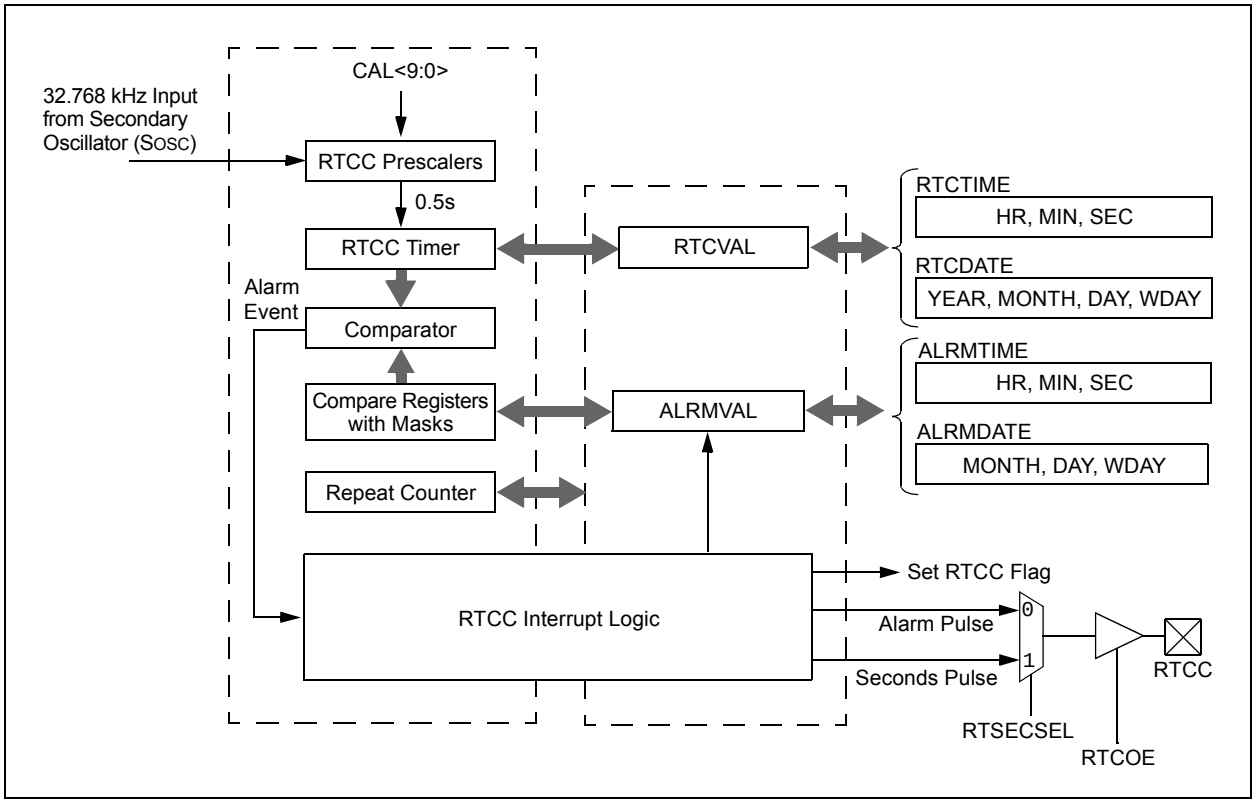
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS60001125), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

Following are some of the key features of this module:

- Time: hours, minutes and seconds
- 24-hour format (military time)
- Visibility of one-half second period
- Provides calendar: day, date, month and year
- Alarm intervals are configurable for half of a second, one second, 10 seconds, one minute, 10 minutes, one hour, one day, one week, one month and one year
- Alarm repeat with decrementing counter
- Alarm with indefinite repeat: Chime
- Year range: 2000 to 2099
- Leap year correction
- BCD format for smaller firmware overhead
- Optimized for long-term battery operation
- Fractional second synchronization
- User calibration of the clock crystal frequency with auto-adjust
- Calibration range: ±0.66 seconds error per month
- Calibrates up to 260 ppm of crystal error
- Requirements: External 32.768 kHz clock crystal
- Alarm pulse or seconds clock output on RTCC pin

FIGURE 21-1: RTCC BLOCK DIAGRAM



REGISTER 21-1: RTCCON: RTC CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
	—	—	—	—	—	—	CAL<9:8>	
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CAL<7:0>							
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON(1,2)	—	SIDL	—	—	—	—	—
7:0	R/W-0	R-0	U-0	U-0	R/W-0	R-0	R-0	R/W-0
	RTSECSEL(3)	RTCCLKON	—	—	RTCWREN(4)	RTCSYNC	HALFSEC(5)	RTCOE

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-26 **Unimplemented:** Read as '0'

bit 25-16 **CAL<9:0>:** RTC Drift Calibration bits, which contain a signed 10-bit integer value

0111111111 = Maximum positive adjustment, adds 511 RTC clock pulses every one minute
•
•
•
0000000001 = Minimum positive adjustment, adds 1 RTC clock pulse every one minute
0000000000 = No adjustment
1111111111 = Minimum negative adjustment, subtracts 1 RTC clock pulse every one minute
•
•
•
1000000000 = Maximum negative adjustment, subtracts 512 clock pulses every one minute

bit 15 **ON:** RTCC On bit(1,2)

1 = RTCC module is enabled
0 = RTCC module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit

1 = Disables the PBCLK to the RTCC when the device enters Idle mode
0 = Continue normal operation when the device enters Idle mode

bit 12-8 **Unimplemented:** Read as '0'

bit 7 **RTSECSEL:** RTCC Seconds Clock Output Select bit(3)

1 = RTCC Seconds Clock is selected for the RTCC pin
0 = RTCC Alarm Pulse is selected for the RTCC pin

bit 6 **RTCCLKON:** RTCC Clock Enable Status bit

1 = RTCC Clock is actively running
0 = RTCC Clock is not running

Note 1: The ON bit is only writable when RTCWREN = 1.

2: When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

3: Requires RTCOE = 1 (RTCCON<0>) for the output to be active.

4: The RTCWREN bit can be set only when the write sequence is enabled.

5: This bit is read-only. It is cleared to '0' on a write to the seconds bit fields (RTCTIME<14:8>).

Note: This register is reset only on a Power-on Reset (POR).

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge1 Status bit
Indicates the status of Edge1 and can be written to control edge source
1 = Edge1 has occurred
0 = Edge1 has not occurred

bit 23 **EDG2MOD:** Edge2 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge2 programmed for a positive edge response
0 = Edge2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = C3OUT pin is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as '0'

bit 15 **ON:** ON Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12 **TGEN:** Time Generation Enable bit**(1)**
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in **Section 30.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

TABLE 30-6: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Parameter No.	**Typical(2)**	**Max.**	**Units**	**Conditions**		
Idle Current (IIDLE): Core Off, Clock on Base Current (Notes 1, 4)						
DC30a	1	1.5	mA	4 MHz **(Note 3)**		
DC31a	2	3	mA	10 MHz		
DC32a	4	6	mA	20 MHz **(Note 3)**		
DC33a	5.5	8	mA	30 MHz **(Note 3)**		
DC34a	7.5	11	mA	40 MHz		
DC37a	100	—	µA	-40°C	3.3V	LPRC (31 kHz) **(Note 3)**
DC37b	250	—	µA	+25°C		
DC37c	380	—	µA	+85°C		

Note 1: The test conditions for IIDLE current measurements are as follows:

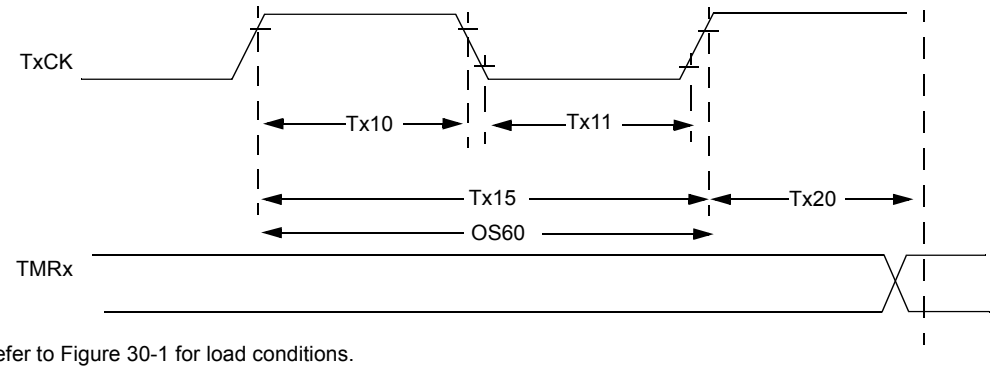
- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Idle mode (CPU core Halted), and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- RTCC and JTAG are disabled

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: This parameter is characterized, but not tested in manufacturing.

4: IIDLE electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

FIGURE 30-6: TIMER1, 2, 3, 4, 5 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-23: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS

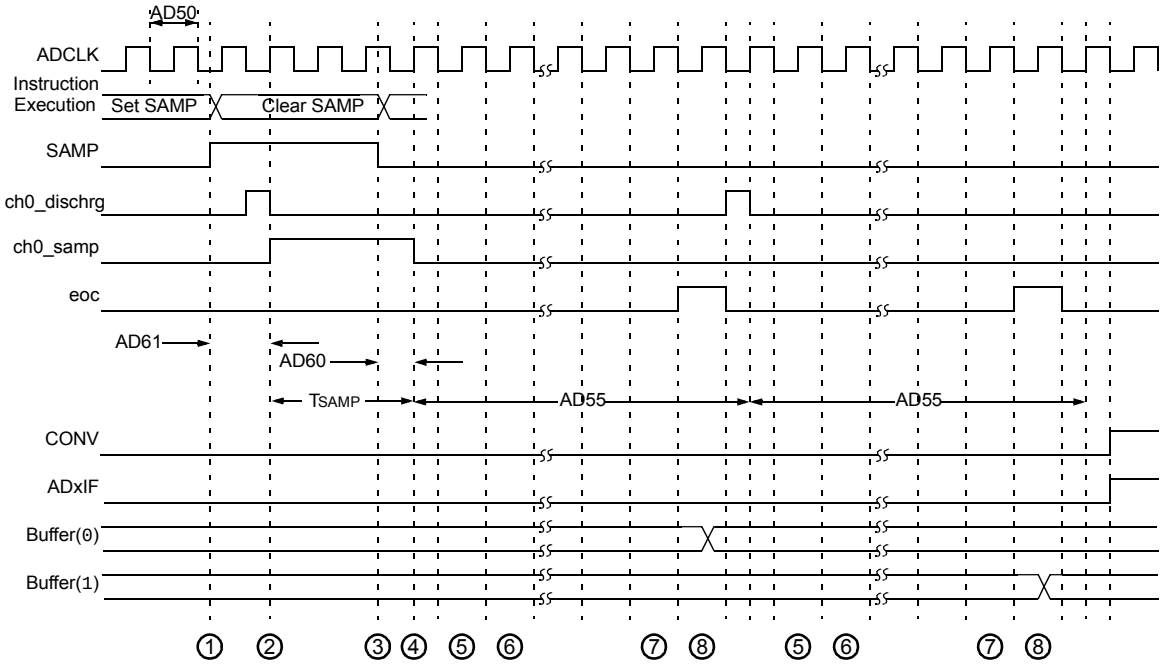
AC CHARACTERISTICS(1)				**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(2)**		**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
TA10	TTXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1 TPB)/N] + 25 ns	—	—	ns	Must also meet parameter TA15
			Asynchronous, with prescaler	10	—	—	ns	—
TA11	TTXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1 TPB)/N] + 25 ns	—	—	ns	Must also meet parameter TA15
			Asynchronous, with prescaler	10	—	—	ns	—
TA15	TTXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of 25 ns or 2 TPB)/N] + 30 ns	—	—	ns	VDD > 2.7V
				[(Greater of 25 ns or 2 TPB)/N] + 50 ns	—	—	ns	VDD < 2.7V
			Asynchronous, with prescaler	20	—	—	ns	VDD > 2.7V **(Note 3)**
				50	—	—	ns	VDD < 2.7V **(Note 3)**
OS60	FT1	SOSC1/T1CK Oscillator Input Frequency Range (oscillator enabled by setting the TCS (T1CON<1>) bit)		32	—	100	kHz	—
TA20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—	—	1	TPB	—

Note 1: Timer1 is a Type A timer.

2: This parameter is characterized, but not tested in manufacturing.

3: N = Prescale Value (1, 8, 64, 256).

FIGURE 30-18: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 0, SSRC<2:0> = 000)



(1) – Software sets ADxCON. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104) in the *"PIC32 Family Reference Manual"*.

(3) – Software clears ADxCON. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

(5) – Convert bit 9.

(6) – Convert bit 8.

(7) – Convert bit 0.

(8) – One TAD for end of conversion.

FIGURE 30-23: EJTAG TIMING CHARACTERISTICS

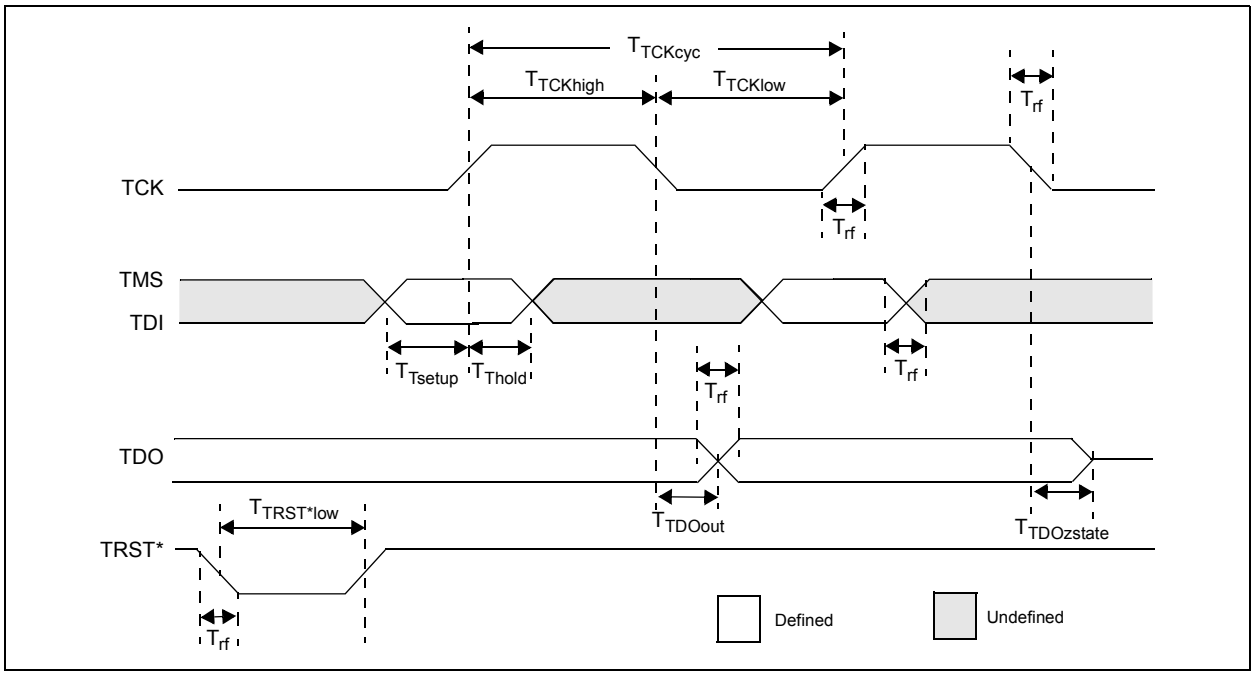


TABLE 30-42: EJTAG TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Description(1)**	**Min.**	**Max.**	**Units**	**Conditions**
EJ1	TTCKCYC	TCK Cycle Time	25	—	ns	—
EJ2	TTCKHIGH	TCK High Time	10	—	ns	—
EJ3	TTCKLOW	TCK Low Time	10	—	ns	—
EJ4	TTSETUP	TAP Signals Setup Time Before Rising TCK	5	—	ns	—
EJ5	TTHOLD	TAP Signals Hold Time After Rising TCK	3	—	ns	—
EJ6	TTDOOUT	TDO Output Delay Time from Falling TCK	—	5	ns	—
EJ7	TTDOZSTATE	TDO 3-State Delay Time from Falling TCK	—	5	ns	—
EJ8	TTRSTLOW	TRST Low Time	25	—	ns	—
EJ9	TRF	TAP Signals Rise/Fall Time, All Input and Output	—	—	ns	—

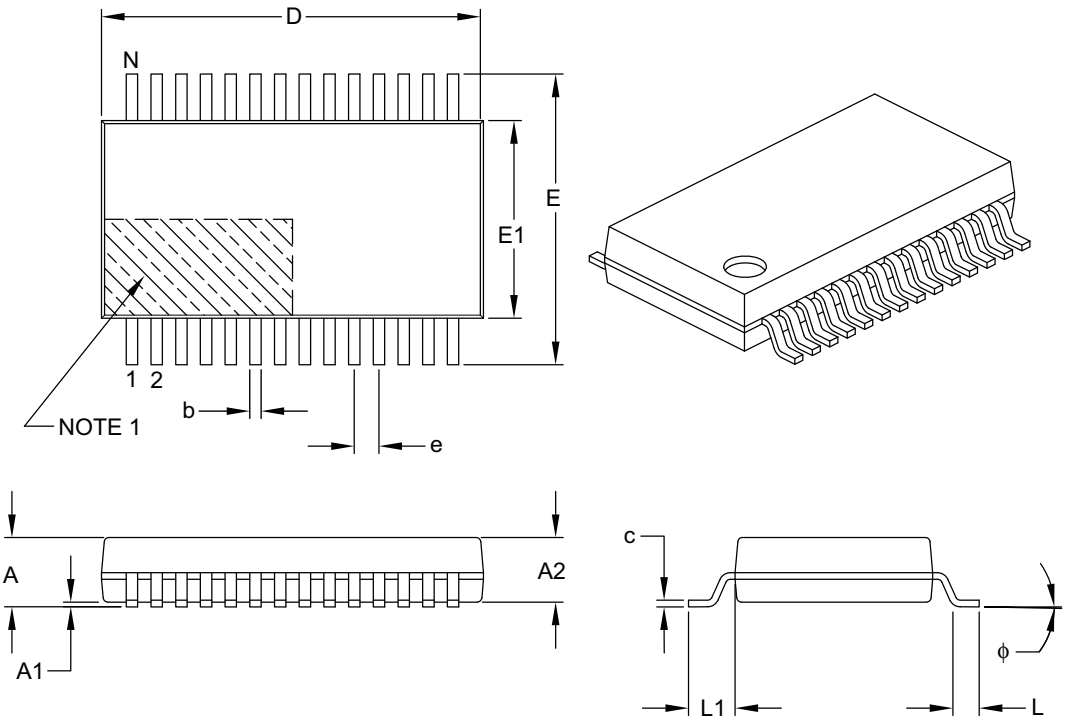
Note 1: These parameters are characterized, but not tested in manufacturing.

33.2 Package Details

This section provides the technical details of the packages.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B